SMP B-COMPONENT PLUS

SILYL MODIFIED POLYMER

KEY BENEFITS

- Controlled curing process
- Faster bonding
- Larger overlap designs possible

PRODUCT DESCRIPTION

Bostik B-Component Plus is a paste like compound which is used as an accelerator to the curing process of Bostik SMP-based adhesives. (B-component Plus is part of the Bostik Dual SMP-system).

APPLICATIONS

Bostik B-Component Plus (1 part B-component on 33 parts of SMP A-component adhesive) significantly speeds up the adhesive curing process and strength build-up.
Bostik B-Component Plus allows for large bonding overlaps, which will not fully cure with a 1-component product due to moisture not being able to diffuse deep enough into the overlap joint.
A and B component are mixed by means of a static mixer. Information on Bostik Dual SMP-system, its components, consumables and usage can be found on a dedicated section of our website.

FEATURES

- Optimal mixing ratio: 1:33; One part B-component Plus on 33 parts of A-component SMP-based adhesive
- Optimal mixing ratio Dual SMP applicator pistol: 1:40 Applicator works uses B-component in 12.5ml cartridge
- pH-value ca. 9

METHOD OF USE

When used together with Bostik ISR 70-05 AP, ISR 70-08 AP and MSR FT, these A-components need to be heated to between 40°C and 60 °C to create an acceptable adhesive flow rate and better mixing during application. Open time of the mixed product can slightly reduce due to heating. It is strongly advised to test the practical open time before using the system.

TECHNICAL DATA

Basic Material		Silyl Modified Polymer (SMP)
Specific Gravity	[g/ml]	ca. 1.4
Color		White, Black
Physical Form		Thixotropic paste
Dry Content	[%]	ca. 74

PACKAGING DESCRIPTION

White: 12,5 ml cartridge
Black: 600ml sausage and 20l pail

STORAGE STABILITY

Bostik B-Component Plus can be stored for 12 months in the original, unopened packaging in a dry place at temperatures between +5°C and +40°C.

FURTHER INFORMATION

The following publication is available on request:
- Material Safety Data Sheets (MSDS).

Specimen curing conditions 23°C/50%RH. Shear strength determined using single lap shear specimens, overlap 25x25 mm, 2 mm bond-line thickness, test speed 50 mm/min. Strength build up represented as a percentage of the final shear strength for the individual A-component. Please refer to the technical data sheet of the A component for further information.

DISCLAIMER

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Bostik SA
51, Esplanade du Général de Gaulle,
92800 Puteaux – France
Smart help: +33 149 007 502
www.bostik.com

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